4.4 TMS70C02, TMS70C42, and TMS70C82 Specifications (Wide Voltage)

Table 4–20. Absolute Maximum Ratings Over Operating Free-Air Temperature Range for the TMS70C02, TMS70C42, and TMS70C82 (Unless Otherwise Noted)

Supply voltage range, V _{CC} † – 0.3V to 7 V
Input voltage range
Output voltage range – 0.3V to VCC+0.3 V
Maximum I/O buffer current (per pin)
Storage temperature range – 55°C to 150°C
I _{CC} , I _{SS} (maximum into pin 25 or 40)
Continuous power dissipation 0.5 W
† Unless otherwise noted, all voltages are with respect to VSS.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

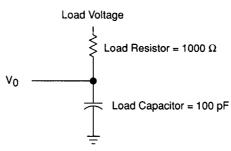
Table 4-21. Recommended Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

			Min	Nom	Max	Unit
Vcc	Supply voltage		2.5		6.0	٧
V _{IH}	High-level input voltage	MC and XTAL2 pins, VCC = 2.5 to 6 V	0.8V _{CC}			٧
		All other input pins, VCC = 3 to 6 V	0.70V _{CC}		*	٧
		All other input pins, V _{CC} = 2.5 to 3 V	0.75V _{CC}			V
V _{IL}	Low-level input voltage	MC and XTAL2 pins, V _{CC} = 2.5 to 6 V			0.2V _{CC}	٧
=		All other input pins, VCC = 2.5 to 6 V			0.3V _{CC}	٧
TA	Operating free-air temperature	Commercial (TMS70C42NL)	0	<u>.</u>	70	°C
		Industrial (TMS70C42NA)	- 40		85	°C

Electrical Characteristics Over Full Range of Operating Conditions for the TMS70C02, Table 4–22. TMS70C42, and TMS70C82

	Parameter	Test Conditions	Min	Typt	Max	Unit
lį	Input current	MC pin, V _{IN} = V _{SS} or V _{CC} All others, V _{IN} = V _{SS} to V _{CC}		±0.1	±5	μА
CI	Input capacitance			5		pF
VOH	High-level output voltage ‡	V _{CC} = 2.5 V, I _{OH} = - 50 mA	2.25	2.4		V
		V _{CC} = 4.0 V, I _{OH} = -0.4 mA	3.2	3.6		V
		$V_{CC} = 5.0 \text{ V}, I_{OH} = -0.7 \text{ mA}$	3.9	4.5		V
		V _{CC} = 6.0 V, l _{OH} = -1.0 mA	4.6	5.4		V
VOL	Low-level output voltage ‡	V _{CC} = 2.5 V, I _{OL} = 0.4 mA		0.2	0.35	V
		V _{CC} = 4.0 V, I _{OL} = 1.6 mA		0.4	0.8	٧
		V _{CC} = 5.0 V, I _{OL} = 2.5 mA		0.6	1.1	٧
		V _{CC} = 6.0 V, l _{OL} = 3.4 mA		0.8	1.4	V
ЮН	Output source current	V _{CC} = 2.5 V, V _{OH} = 2.25 V	-50	-200		μΑ
		V _{CC} = 4.0 V, V _{OH} = 3.2 V	-0.4	-1.4		mA
		V _{CC} = 5.0 V, V _{OH} = 3.9 V	-0.7	-2.2		mA
		V _{CC} = 6.0 V, V _{OH} = 4.6 V	-1.0	-3.3		mA
loL	Output sink current	V _{CC} = 2.5 V, V _{OL} = 0.35 V	0.4	0.9		mA
		V _{CC} = 4.0 V, V _{OL} = 0.8 V	1.6	3.5		mA
		V _{CC} = 5.0 V, V _{OL} = 1.1 V	2.5	5.5		mA
		V _{CC} = 6.0 V, V _{OL} = 1.4 V	3.4	8.0		mA

Figure 4–15. Output Loading Circuit for Test for the TMS70C02, TMS70C42, and TMS70C82



Note: Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

 [†] V_{CC} = 5 V, T_A = 25°C
‡ Output levels ensure 400 mV of noise margin over specified input levels.

Table 4–23. Supply Current Requirements for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Test Co	onditions	Min Typ	Max	Unit
lcc	Operating mode	f _{OSC} = 7.0 MHz,	V _{CC} = 5.0 V	17	24.5	mA
		$f_{OSC} = 3.0 \text{ MHz},$	V _{CC} = 5.0 V	7.2	10.5	mA
		$f_{OSC} = 0.5 \text{ MHz},$	V _{CC} = 5.0 V	1.2	1.8	mA
		f _{osc} = Z MHz,	V _{CC} = 5.0 V	2.4	3.5	mA/ MHz
		$f_{OSC} = 0.5 \text{ MHz},$	V _{CC} = 2.5 V	0.4	1.2	mA
ICC	Wake-up mode 1	$f_{OSC} = 7.0 \text{ MHz},$	V _{CC} = 5.0 V	2400	5600	μА
	(one timer and UART active)	$f_{OSC} = 3.0 \text{ MHz},$	V _{CC} = 5.0 V	1200	3300	μА
		f _{osc} = 0.5 MHz,	V _{CC} = 5.0 V	250	800	μ Α '
lcc	Wake-up mode 2	f _{osc} = 7.0 MHz,	V _{CC} = 5.0 V	960	3400	μА
	(one timer active and UART inactive)	f _{OSC} = 3.0 MHz,	V _{CC} = 5.0 V	480	2000	μА
		f _{OSC} = 0.5 MHz,	V _{CC} = 5.0 V	140	550	μА
lcc	Wake-up mode 3	f _{osc} = 7.0 MHz,	V _{CC} = 5.0 V	1500	2400	μА
	(UART active only)	fosc = 3.0 MHz,	V _{CC} = 5.0 V	800	1500	μA
		f _{osc} = 0.5 MHz,	V _{CC} = 5.0 V	180	600	μA
lcc	Halt OSC-ON	$f_{OSC} = 7.0 \text{ MHz},$	V _{CC} = 5.0 V	560	1280	μА
		f _{OSC} = 3.0 MHz,	V _{CC} = 5.0 V	240	560	μА
		f _{osc} = 1.0 MHz,	V _{CC} = 5.0 V	80	200	μА
		fosc = Z MHz		(See Not	e 2)	μΑ
lcc	Hait OSC-OFF			5	10	μА

Notes: 1) All inputs = V_{CC} or V_{SS} (except XTAL2). All I/O and output pins are open.

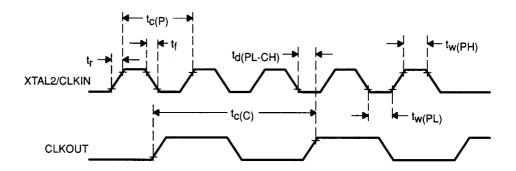
2) Maximum current = 180(Z) + 20 μA.

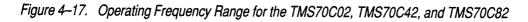
Table 4–24. Recommended Crystal/Clockin Operating Conditions Over Full Operating Range for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Test Conditions	Min	Typ†	Max	Unit
fosc	Crystal frequency	V _{CC} = 2.5 V	0.5		0.8	MHz
		V _{CC} = 4.0 V	0.5		5.0	MHz
		V _{CC} = 5.0 V	0.5		7.0	MHz
		V _{CC} = 6.0 V	0.5		7.5	MHz
	CLKIN duty cycle		47		53	%
t _{c(P)}	CLKIN cycle time	V _{CC} = 2.5 V	333		2000	ns
		V _{CC} = 4.0 V	167		2000	ns
		V _{CC} = 5.0 V	143		2000	ns
		V _{CC} = 6.0 V	133		2000	ns
^t c(C)	Internal state cycle time	V _{CC} = 2.5 V	666		4000	ns
		V _{CC} = 4.0 V	333		4000	ns
		V _{CC} = 5.0 V	286		4000	ns
		V _{CC} = 6.0 V	267		4000	ns
tw(PH)	CLKIN pulse duration high		50			ns
tw(PL)	CLKIN pulse duration low		50			ns
t _r	CLKIN rise time		1		30	ns
tf	CLKIN fall time				30	ns
td(PL-CH)	CLKIN fall to CLKOUT rise	· · · · · · · · · · · · · · · · · · ·		110	250	ns

[†] $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}.$

Figure 4–16. Clock Timing for the TMS70C02, TMS70C42, and TMS70C82





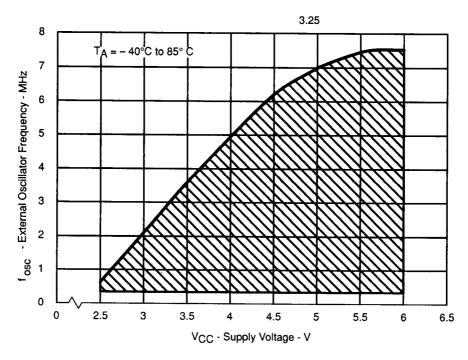


Figure 4–18. Typical Operating Current vs. Supply Voltage for the TMS70C02, TMS70C42, and TMS70C82

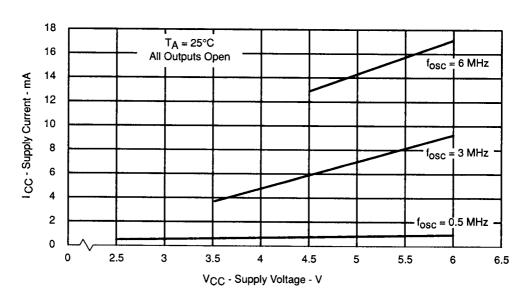


Figure 4–19. Typical Operating I_{CC} vs. Oscillator Frequency for the TMS70C02, TMS70C42, and TMS70C82

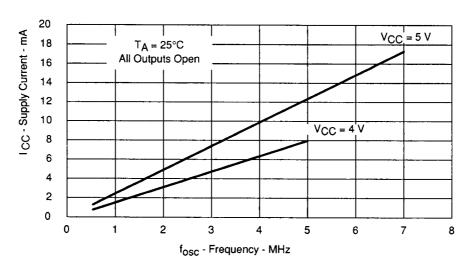


Figure 4-20. Typical Operating Current vs. Supply Voltage for the TMS70C02, TMS70C42, and TMS70C82

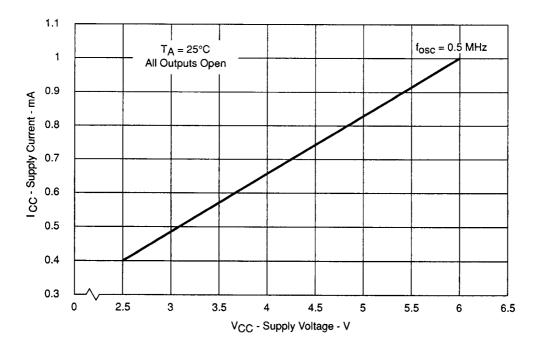


Figure 4–21. Typical Output Source Characteristics for the TMS70C02, TMS70C42, and TMS70C82

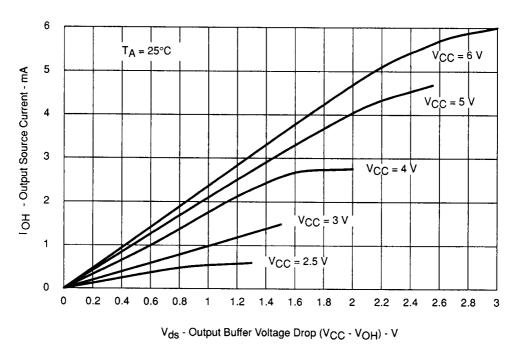
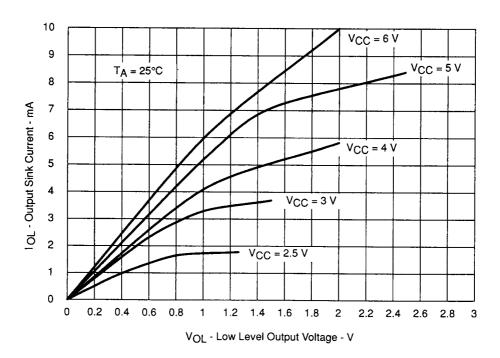


Figure 4-22. Typical Output Sink Characteristics for the TMS70C02, TMS70C42, and TMS70C82



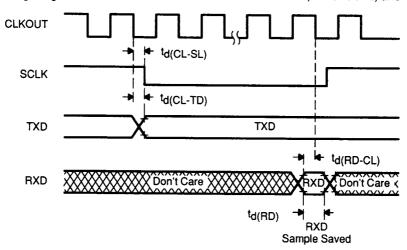
4.4.1 Serial Port Timing

4.4.1.1 Internal Serial Clock

Table 4-25. Timing Parameters for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Тур	Unit
^t d(CL-SL)	CLKOUT low to SCLK low	1/4 t _{c(C)}	ns
^t d(CL-TD)	CLKOUT low to new TXD data	1/4 t _{C(C)}	ns
^t d(RD-CL)	RXD data valid before CLKOUT low	1/4 t _{c(C)}	ns
t _{d(RD)}	RXD data valid time	1/2 t _{c(C)}	ns

Figure 4-23. Timing Diagram for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes: 1) The CLKOUT signal is not available in single-chip mode.

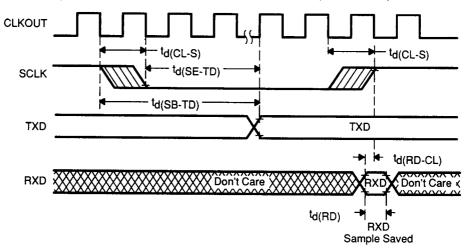
2) CLKOUT = $t_{C(C)}$.

4.4.1.2 External Serial Clock

Table 4-26. Timing Parameters for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Тур	Unit
^t d(RD-CL)	RXD data valid before CLKOUT low	1/4 t _C (C)	ns
^t d(RD)	RXD data valid time	1/2 t _{c(C)}	ns
td(SB-TD)	Start of SCLK sample to new TXD data	3 1/4 t _{c(C)}	ns
^t d(SE-TD)	End of SCLK sample to new TXD data	2 1/4 t _C (C)	ns
td(CL-S)	Clockout low to SCLK transition	t _C (C)	ns

Figure 4-24. Timing Diagram for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes: 1) The CLKOUT signal is not available in single-chip mode.

2) CLKOUT = $t_{C(C)}$.

3) SCLK sampled; if SCLK = 1 then 0, fall transition found.

4) SCLK sampled; if SCLK = 0 then 1, rise transition found.

4.5 TMS70C02, TMS70C42, and TMS70C82 Specifications (5V \pm 10%)

Table 4–27. Absolute Maximum Ratings Over Operating Free-Air Temperature Range for the TMS70C02, TMS70C42, and TMS70C82 (Unless Otherwise Noted)

Supply voltage range, V _{CC} † – 0.3 V to 7 V
Input voltage range 0.3 V to V _{CC} +0.3 V
Output voltage range 0.3 V to V _{CC} +0.3 V
Maximum I/O buffer current (per pin)
Storage temperature range – 55°C to 150°C
ICC, ISS (maximum into pin 25 or 40
Continuous power dissipation
† Unless otherwise noted, all voltages are with respect to VSS.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute maximum rated conditions for extended periods

Table 4-28. Recommended Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

may affect device reliability.

		-	Min	Nom	Max	Unit
VCC	Supply voltage		4.5		5.5	٧
VIH	High-level input voltage	MC and XTAL2 pins	0.8V _{CC}			٧
		All other input pins	0.7V _{CC}			٧
VIL	Low-level input voltage	MC and XTAL2 pins			0.3V _{CC}	٧
		All other input pins			0.2V _{CC}	٧
TA	Operating temperature	Commercial (TMS70C42NL)	0		70	°C
		Industrial (TMS70C42NA)	-40		85	°C

Table 4–29. Electrical Characteristics Over Full Range of Operating Conditions for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Test Conditions	Min	Typt	Max	Unit
ų	Input leakage current	MC pin, V _{IN} = V _{SS} or V _{CC} All others, V _{IN} = V _{SS} to V _{CC}		±0.1	±5	μА
CI	Input capacitance			5		pF
۷он	High-level output voltage	$V_{CC} = 5.0 \text{ V}, I_{OH} = -0.3 \text{ mA}$	VCC-0.05	4.7		V
VOL	Low-level output voltage	V _{CC} = 5.0 V, I _{OL} = 1.4 mA		0.2	0.4	V
ЮН	High-level output source current	V _{OH} = V _{CC} - 0.5 V	-0.3	-1.2		mA
		V _{OH} = 2.5 V min	-1.0	-3.0		mA
loL	Output sink current	V _{OL} = 0.4 V	1.4	2.0		mA

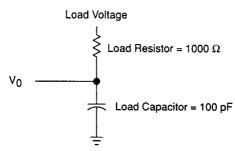
[†] Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Table 4-30. AC Characteristics for Input/Output Ports† for the TMS70C02, TMS70C42, and TMS70C82

Parameter	Test Conditions	Min	Typt	Max	Unit
t _{r(IO)} I/O port output rise time	C _{load} = 15 pF, V _{CC} = 5 V		35	60	ns
tf(IO) I/O port output fall time	C _{load} = 15 pF, V _{CC} = 5 V		20	50	ns

[†] Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Figure 4-25. Output Loading Circuit for Test for the TMS70C02, TMS70C42, and TMS70C82



Note: Rise and fall times are measured between the maximum low level and the minimum high level using the 10% and 90% points.

Figure 4–26. Measurement Points for Switching Characteristics for the TMS70C02, TMS70C42, and TMS70C82

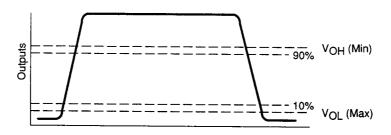


Table 4–31. Supply Current Requirements for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Test Conditions	Min Typ	Max	Unit
ō	Supply current	f _{OSC} = 6.0 MHz	15	24	mA
		f _{osc} = 3.0 MHz	7.2	12	mA
		f _{osc} = 1.0 MHz	2.4	4.0	mA
		f _{OSC} = Z MHz	2.4	4.0	mA/ MHz
lcc	Wake-up mode 1	f _{OSC} = 6.0 MHz	2400	5400	μА
	(one timer and UART active)	f _{osc} = 3.0 MHz	1200	2900	μА
		f _{OSC} = 1.0 MHz	650	1500	μА
ICC	Wake-up mode 2	f _{OSC} = 6.0 MHz	960	3200	μА
	(one timer active, and UART inactive)	f _{OSC} = 3.0 MHz	480	1800	μА
		f _{OSC} = 1.0 MHz	350	1000	μА
lcc	Wake-up mode 3	f _{OSC} = 6.0 MHz	1500	2200	μА
	(UART active only)	f _{OSC} = 3.0 MHz	800	1300	μА
		f _{OSC} = 1.0 MHz	400	1100	μА
ICC	Halt OSC-ON	fosc = 6.0 MHz	480	1120	μА
		f _{osc} = 3.0 MHz	240	560	μА
		f _{OSC} = 1.0 MHz	80	200	μА
		f _{osc} = Z MHz	(Se	e Note 2)	μА
Icc	Halt OSC-OFF		5	10	μА

Notes: 1) All inputs = V_{CC} or V_{SS} (except XTAL2). All output pins are open.

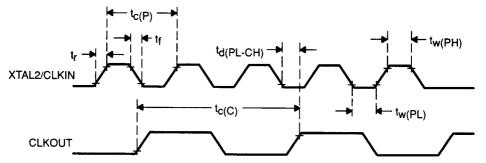
2) Maximum current = $180(Z) + 20 \mu A$.

Table 4–32. Recommended Crystal/Clockin Operating Conditions Over Full Operating Range for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Min	Тур	Max	Unit
fosc	CLKIN frequency	0.5		6.0	MHz
	CLKIN duty cycle	45		55	%
t _{c(P)}	CLKIN cycle time	167		2000	ns
^t c(C)	Internal state cycle time	333		4000	ns
t _{w(PH)}	CLKIN pulse duration high	70			ns
^t w(PL)	CLKIN pulse duration low	70			ns
t _r	CLKIN rise time			30	ns
tf	CLKIN fall time			30	ns
^t d(PL-CH)	CLKIN fall to CLKOUT rise delay		110	250	ns

[†] $V_{CC} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$

Figure 4-27. Clock Timing for the TMS70C02, TMS70C42, and TMS70C82



Note: Period of internal clock $t_{c(C)} = 2 \times t_{c(P)} = 2 / f_{osc}$. Timings are given in $t_{c(C)}$.

Table 4-33. Memory Interface Timings† for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Min	Typt	Max	Unit
^t c(C)	CLKOUT cycle time	333		4000	ns
tw(CH)	CLKOUT high pulse duration	0.5t _{C(C)} - 90	0.5t _{c(C)}	0.5t _{C(C)} +90	ns
^t w(CL)	CLKOUT low pulse duration	0.5t _{C(C)} - 90	0.5t _{c(C)}	0.5t _{C(C)} +90	ns
^t d(CH-JL)	Delay time, CLKOUT rise to ALATCH fall	0.5t _{C(C)} - 50	0.5t _{c(C)}		ns
^t w(JH)	ALATCH high pulse duration	0.25t _{C(C)} -50	0.25t _{c(C)}	· · · · · · · · · · · · · · · · · · ·	ns
^t su(HA–JL)	Setup time, high address valid before ALATCH fall	0.25t _{C(C)} - 45	0.25t _{C(C)}		ns
tsu(LA-JL)	Setup time, low address valid before ALATCH fall	0.25t _{C(C)} - 45	0.25t _{C(C)}		ns
^t d(JL–LA)	Delay time, low address valid after ALATCH fall	0.5t _{C(C)} - 35	0.5t _{C(C)}		ns
tsu(RW-JL)	Setup time, R/W valid before ALATCH fall	0.25t _{C(C)} - 40	0.25t _{C(C)}		ns
th(EH-RW)	Hold time, R/W valid after ENABLE rise	0.5t _{C(C)} - 60	0.5t _{c(C)}		ns
th(EH-HA)	Hold time, high address valid after ENABLE rise	0.5t _{C(C)} - 60	0.5t _{C(C)}		ns
^t su(Q–EH)	Setup time, data out valid before ENABLE rise	0.5t _{C(C)} -70	0.5t _{C(C)}		ns
^t h(EH–Q)	Hold time, data out valid after ENABLE rise	0.5t _{C(C)} - 60	0.5t _{c(C)}		ns
^t d(LA–EL)	Delay time, low address high-Z to ENABLE fall	.25t _{C(C)} - 45	0.25t _{C(C)}		ns
td(EH-A)	Delay time, ENABLE rise to next address drive	0.5t _{C(C)} -60	0.5t _{C(C)}		ns
^t d(EL–D)	Delay time, data in after ENABLE fall	0.75t _{C(C)} -160	0.75t _{c(C)}		ns
^t a(A–D)	Access time, data in from valid address	1.5t _{C(C)} - 200	1.5t _{C(C)} - 100		ns
^t d(A–EH)	Delay time, ENABLE high after address valid	1.5t _{C(C)} - 50	1.5t _{c(C)}		ns
^t h(EH–D)	Hold time, Data input valid after ENABLE rise	0			ns
^t d(EH–JH)	Delay time, ENABLE rise to ALATCH rise	0.5t _{C(C)} - 60	0.5t _C (C)	·	ns
^t d(CH–EL)	Delay time, CLKOUT rise to ENABLE fall		30		ns

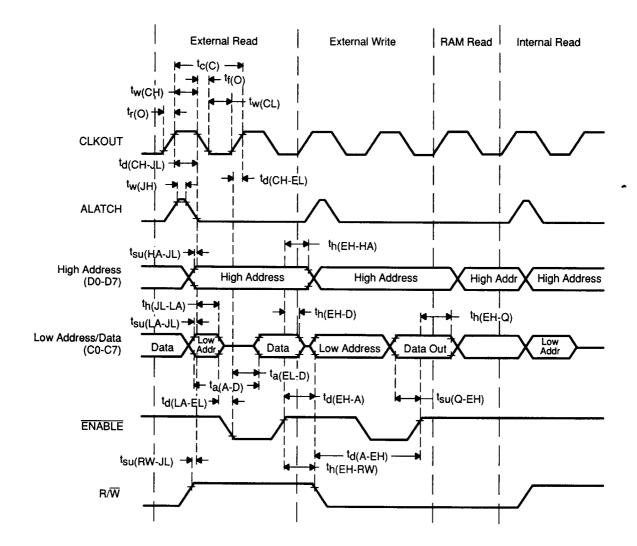
[†] $V_{CC} = 5 \text{ V} \pm 10\%$, $t_{C(C)} = 2/\text{freq}$ CLKIN duty cycle = 50% $t_{OSC} = 0.5 \text{ to } 6.0 \text{ MHz}$

Table 4–34. Memory Interface Timings at 6 MHz† for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Min	Typt	Max	Unit
t _C (C)	CLKOUT cycle time		333		ns
^t w(CH)	CLKOUT high pulse duration	76	166	252	ns
^t w(CL)	CLKOUT low pulse duration	76	162	252	ns
fd(CH-JL)	Delay time, CLKOUT rise to ALATCH fall	116	166		ns
^t w(JH)	ALATCH active duration	33	83		ns
^t su(AH–JL)	Setup time, high address valid before ALATCH fall	38	83		ns
^t su(LA–JL)	Setup time, low address valid before ALATCH fall	38	83		ns
^t d(JL–LA)	Delay time, low address hold after ALATCH fall	131	166		ns 💂
^t d(RW-JL)	Delay time, R/W valid before ALATCH fall	43	83		ns
th(EH-RW)	Hold time, R/W valid after ENABLE rise	106	166		ns
th(EH-HA)	Hold time, high address valid after ENABLE rise	106	166		ns
tsu(Q-EH)	Setup time, data out valid before ENABLE rise	96	166		ns
th(EH-Q)	Hold time, data out valid after ENABLE rise	106	166	•	ns
td(LA-EL)	Delay time, low address high-Z to ENABLE fall	38	83		ns
td(EH-A)	Delay time, ENABLE rise to next address drive	106	166		ns
td(EL-D)	Delay time, data in after ENABLE fall	90	250		ns
ta(A-D)	Access time, data in from valid address	300	400		ns
td(A-EH)	Delay time, ENABLE high after address valid	450	500		ns
th(EH-D)	Hold time, data input valid after ENABLE rise	0			ns
td(EH−JH)	Delay time, ENABLE rise to ALATCH rise	106	166		ns
td(CH-EL)	Delay time, CLKOUT rise to ENABLE fall		30		ns

[†] $V_{CC} = 5 \text{ V} \pm 10\%$, $t_{C(C)} = 2/\text{freq}$ CLKIN duty cycle = 50% $f_{OSC} = 0.5 \text{ to } 6.0 \text{ MHz}$

Figure 4–28. Read and Write Cycle Timing for the TMS70C02, TMS70C42, and TMS70C82



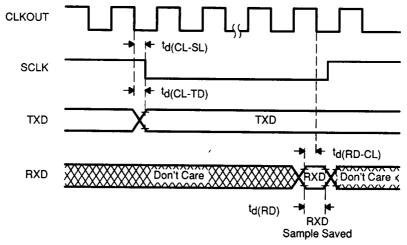
4.5.1 Serial Port Timing

4.5.1.1 Internal Serial Clock

Table 4-35. Timing Parameters for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Тур	Unit
^t d(CL-SL)	CLKOUT low to SCLK low	1/4 t _{c(C)}	ns
td(CL-TD)	CLKOUT low to new TXD data	1/4 t _{c(C)}	ns
^t d(RD-CL)	RXD data valid before CLKOUT low	1/4 t _{c(C)}	ns
^t d(RD)	RXD data valid time	1/2 t _{c(C)}	ns -

Figure 4-29. Timing Diagram for Internal Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes: 1) The CLKOUT signal is not available in single-chip mode.

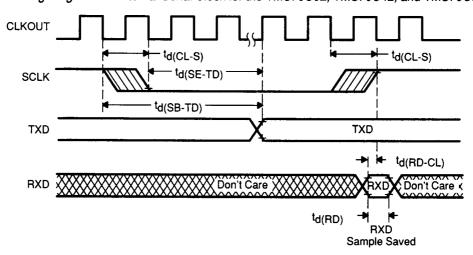
2) CLKOUT = $t_{C(C)}$.

4.5.1.2 External Serial Clock

Table 4-36. Timing Parameters for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82

	Parameter	Тур	Unit
^t d(RD-CL)	RXD data valid before CLKOUT low	1/4 t _{C(C)}	ns
^t d(RD)	RXD data valid time	1/2 t _{c(C)}	ns
^t d(SB-TD)	Start of SCLK sample to new TXD data	3 1/4 t _{C(C)}	ns
^t d(SE-TD)	End of SCLK sample to new TXD data	2 1/4 t _{C(C)}	ns
^t d(CL-S)	Clockout low to SCLK transition	t _C (C)	ns

Figure 4-30. Timing Diagram for External Serial Clock for the TMS70C02, TMS70C42, and TMS70C82



Notes: 1) The CLKOUT signal is not available in single-chip mode.

- 2) $CLKOUT = t_{C(C)}$.
- 3) SCLK sampled; if SCLK = 1 then 0, fall transition found.
- 4) SCLK sampled; if SCLK = 0 then 1, rise transition found.